

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	0	"10674317"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 10:34
S2	1	"10/674317"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 17:12
S3	291	361/799.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 11:02
S4	4257	361/783,784,792-798.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 11:03
S5	11930	ground near3 pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 11:03
S6	1597907	semiconductor or semi\$conductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 11:04
S7	68	S4 and S5 and S6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 11:10
S8	154	solder near2 extrusion	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 11:12

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S9	37053	solder near (ball or bump)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 11:12
S10	2085460	resin	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 11:12
S11	155733	(bismaleimide near triazine) or polyimide FR-4 or FR-5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 11:14
S12	5524	S5 and S6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 11:14
S13	5735	S9 and S10 and S11	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 11:14
S14	245	S12 and S13	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 11:21
S15	0	ball near grid near array	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 11:21
S16	20303	ball near grid near array	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 11:22

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S17	13237	S6 and S16	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 11:22
S18	7692	S17 and S9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 11:22
S19	468	S18 and S5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 11:25
S20	7547	solder near2 mask	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 11:25
S21	1168	S20 and S18	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 11:26
S22	124	S20 and S19	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 11:26
S23	39423	ground near2 plane	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 11:38
S24	20649	matrix near2 array	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 11:38

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S25	336	S24 and S23	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 11:39
S26	27	S25 and S5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 11:40
S27	63	non near solder near mask near defined	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 11:47
S28	92	nsmd	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 15:36
S29	11	nsmd and ground	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 11:48
S30	3	hyper and lightspeed and antenna	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 14:35
S31	373	hyper and light and speed and antenna	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 14:35
S32	1	"hyper light speed".ti.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 14:35

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S33	113	nsmd or (non\$solder near mask near defined)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 15:37
S34	113	nsmd or (non\$solder near mask near defined) or (non near solder near mask near defined)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 15:37
S35	14	S33 and ground	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 15:37
S36	3858	flip near chip near mounting	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 17:13
S37	1513	S36 and S9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 17:14
S38	441	S36 with S9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 17:30
S39	121	S36 with "solder ball"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 17:31
S40	2	"5841075".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/11 13:44
S41	10	("5710071" "5866442" "5923959" "6046076").PN. OR ("6383846").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/12 09:38

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S42	35	("20010008305" "5220490" "5410107" "5508556" "5801440" "5818102" "5841191" "5864470" "5866942" "5894410" "5903050" "5982632" "6034427" "6037677" "6057596" "6104258" "6137168" "6198635" "6214638" "6268238" "6274925" "6278264").PN. OR ("6448639").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/12 09:43
S43	48	("4835598" "5397917" "5450290" "5467253" "5561322" "5592025" "5619070" "5640047").PN. OR ("5866942").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/12 09:59
S44	1	("20040021156").PN. OR ("6916685").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/16 15:31
S45	1	("20040021156").PN. OR ("6916685").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/16 15:32
S46	5	("5894984" "6034427" "6108212" "6194782" "6281581").PN. OR ("6787918").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/17 08:25
S47	77	"non solder mask defined" or nsdm	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/17 08:27
S48	16	"non solder mask define" or nsdm	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/17 08:26
S49	35	("20010008305" "5220490" "5410107" "5508556" "5801440" "5818102" "5841191" "5864470" "5866942" "5894410" "5903050" "5982632" "6034427" "6037677" "6057596" "6104258" "6137168" "6198635" "6214638" "6268238" "6274925" "6278264").PN. OR ("6448639").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/17 09:17
S50	15	("6057596").URPN.	USPAT	OR	ON	2006/04/17 09:21
S51	20	("4746966" "5632631" "5641988" "5796169" "5895968").PN. OR ("6057596").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/17 09:21

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S52	2	nsmd with ground	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 10:24
S53	3	(nsmd "non solder mask define" "non solder mask defined") with ground	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 10:56
S54	6187	174/255,256,260.ccls. 361/783,760. ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 11:11
S55	6187	S54	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 11:11
S56	659	S54 and (ground near plane)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 11:12
S57	357	S55 and (solder near mask)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 11:12
S58	1	10/322308	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 14:48